

# MECHANICAL CASE OUTLINE

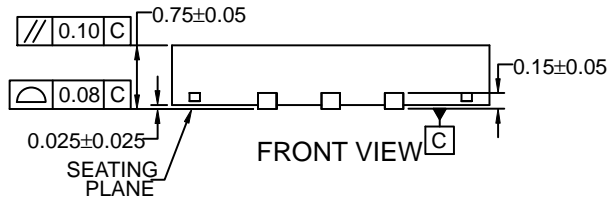
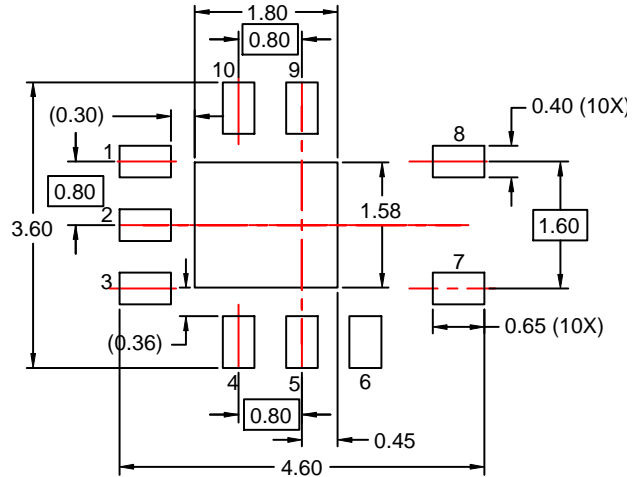
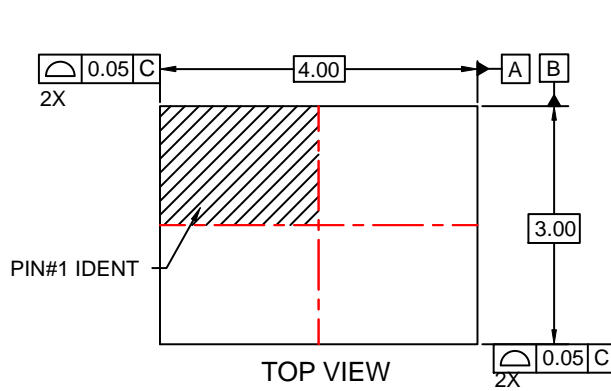
## PACKAGE DIMENSIONS

ON Semiconductor®



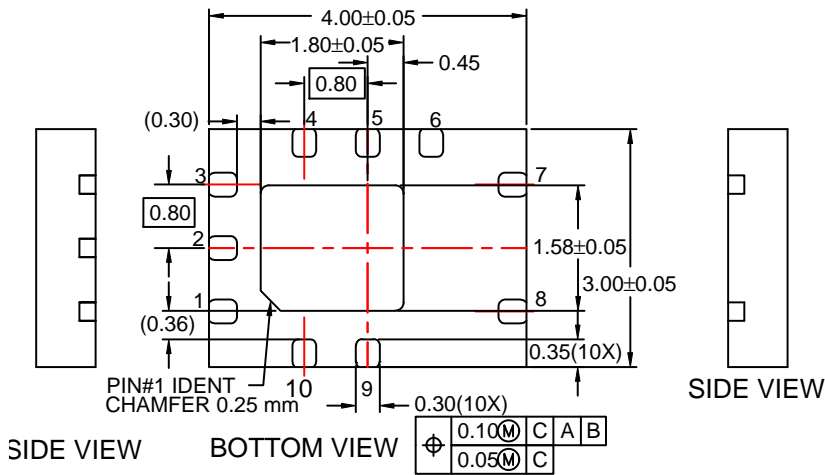
**WDFN10 4x3, 0.8P**  
CASE 511CT  
ISSUE O

DATE 31 JUL 2016



**NOTES:**

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MO-220.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



Φ	0.10(M)	C	A	B
	0.05(M)	C		

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WDFN10 4X3, 0.8P</b>	<b>PAGE 1 OF 2</b>

